

General Description

The WSK150N10 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSK150N10 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

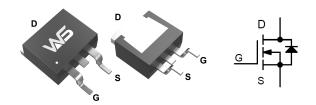
Product Summery

BV _{DSS}	R _{DSON}	I _D
100V	$3.7 m\Omega$	150A

Applications

- Power Management in TV Converter.
- DC-DC Converter
- LED TV Back Light

TO-263-2L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter Rating		Units		
V_{DS}	Drain-Source Voltage 100		V		
V_{GS}	Gate-Source Voltage	±25	V		
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	150	Α		
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ 10V ¹	Continuous Drain Current, V _{GS} @ 10V ¹ 90			
I _{DM}	Pulsed Drain Current ² ,T _C =25°C 600		Α		
EAS	Avalanche Energy, Single pulse	545	mJ		
I _{AS}	Avalanche Current, Single pulse 60		Α		
P _D @T _C =25℃	Total Power Dissipation ⁴ 225		W		
T _{STG}	Storage Temperature Range -55 to 150		$^{\circ}$		
TJ	Operating Junction Temperature Range	150	$^{\circ}$		

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{0JA}	Thermal Resistance Junction-Ambient ¹		50	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹		0.55	°C/W



Electrical Characteristics (T_J=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25℃ , I _D =1mA		0.096		V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =80A		3.7	4.2	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V V 1 050 A	2.5	3.0	4.5	٧
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-5.5		mV/℃
,	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =25℃			1	uA
I _{DSS}		V_{DS} =80V , V_{GS} =0V , T_{J} =55 $^{\circ}$ C			5	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20 V$, V_{DS} = $0 V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =50A		120		S
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		0.7	1.5	Ω
Qg	Total Gate Charge (10V)			80		
Q_{gs}	Gate-Source Charge	V _{DS} =80V , V _{GS} =10V , I _D =80A		33		nC
Q_{gd}	Gate-Drain Charge			18		
T _{d(on)}	Turn-On Delay Time			28		
Tr	Rise Time	V _{DD} =50V , V _{GS} =10V ,		55		
T _{d(off)}	Turn-Off Delay Time	R _G =5Ω, I _D =80A		98		
T _f	Fall Time			24		
C _{iss}	Input Capacitance			4120		
Coss	Output Capacitance	V _{DS} =50V , V _{GS} =0V , f=1MHz		1250		pF
C _{rss}	Reverse Transfer Capacitance			65		

Diode Characteristics

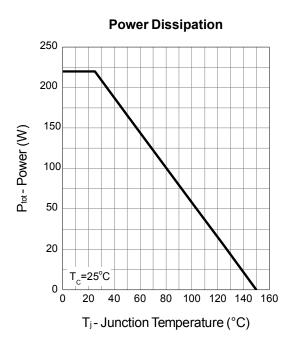
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			80	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =50A , T _J =25℃		0.8	1.3	V
t _{rr}	Reverse Recovery Time	IF=50A,dI/dt=100A/μs,T _J =25℃		85		nS
Qrr	Reverse Recovery Charge			200		nC

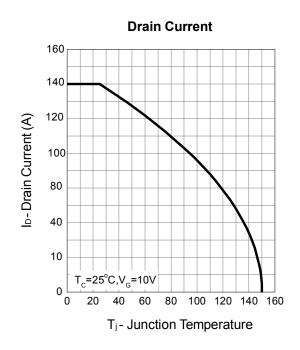
- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec. 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2% 3.The EAS data shows Max. rating . The test condition is V_{DS}=80V,V_{GS}=10V,L=0.1mH,

- 5. The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

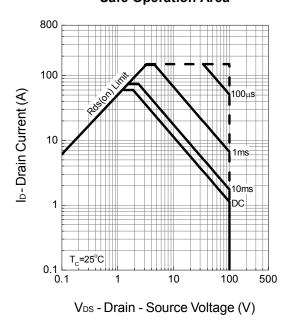


Typical Operating Characteristics

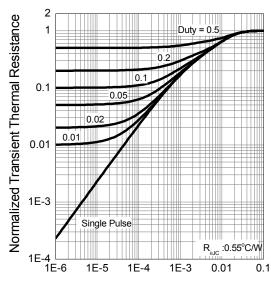




Safe Operation Area



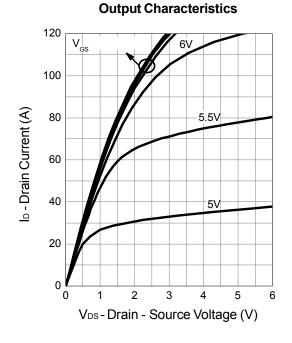
Thermal Transient Impedance



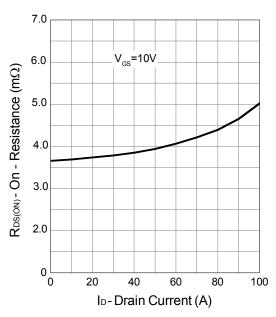
Square Wave Pulse Duration (sec)



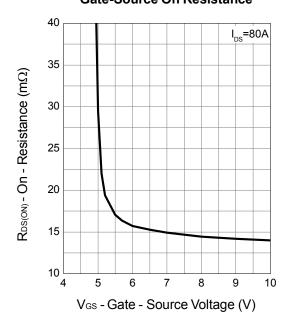
Typical Operating Characteristics



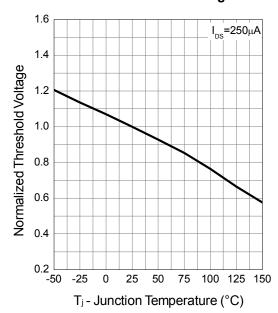
Drain-Source On Resistance



Gate-Source On Resistance

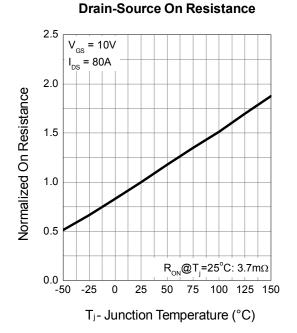


Gate Threshold Voltage

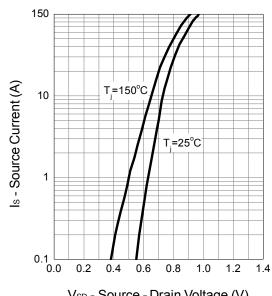




Typical Operating Characteristics

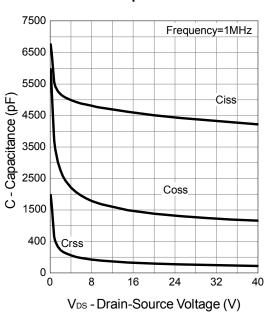


Source-Drain Diode Forward

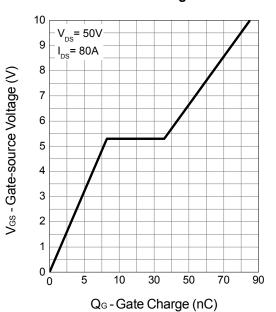


VsD - Source - Drain Voltage (V)

Capacitance



Gate Charge





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